

RD3G07BAT

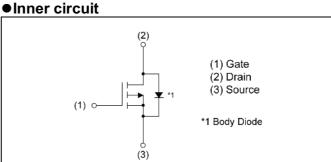
Pch -40V -70A Power MOSFET

V <sub>DSS</sub>	-40V
R <sub>DS(on)</sub> (Max.)	7.1mΩ
Ι <sub>D</sub>	±70A
P <sub>D</sub>	101W

# 70A D1W

DPAK

Outline



(2)

# Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TL1
	Marking	RD3G07BAT

# • Application

Switching

Features

1) Low on - resistance

4) Parallel use is easy

2) Fast switching speed

3) Drive circuits can be simple

5) Pb-free plating ; RoHS compliant

# • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	-40	V
Continuous drain current	۱ <sub>D</sub> *1	±70	А
Pulsed drain current	I <sub>DP</sub> *2	±140	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	-35	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	88	mJ
Power dissipation	P <sub>D</sub> <sup>*1</sup>	101	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# •Thermal resistance

Parameter	Symbol	Values			Unit
Falameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}^{*1}$	-	-	1.23	°C/W

# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions	Values			Linit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = -1mA$ referenced to 25°C		-	-22	-	mV/°C	
Zero gate voltage drain current	$I_{DSS}$ $V_{DS}$ = -40V, $V_{GS}$ = 0V		-	-	-1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS}$ = ±20V, $V_{DS}$ = 0V		-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -1mA$	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	•		-	3.7	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = -10V, I <sub>D</sub> = -70A	-	5.7	7.1		
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -35A	-	6.9 8.7		- mΩ	
Gate resistance	R <sub>G</sub>	R <sub>G</sub> f = 1MHz, open drain		4.1	-	Ω	
Forward Transfer Admittance	$ Y_{f_0} ^4  V_{D_0} = -5V _{D_0} = -35A$		36	-	-	S	

\*1 T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.1mH, V<sub>DD</sub> = -20V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>i</sub> = 25°C Fig.3-1,3-2

\*4 Pulsed



# • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Cumph of	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub> V <sub>GS</sub> = 0V		-	5550	-		
Output capacitance	C <sub>oss</sub> V <sub>DS</sub> = -20V		-	640	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	C <sub>rss</sub> f = 1MHz		485	-		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -20V, V_{GS} = -10V$	-	22	-		
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = -35A	-	90	-		
Turn - off delay time	t <sub>d(off)</sub> *4	$t_{d(off)}{}^{*4} \qquad R_L \simeq 0.57 \Omega$		270	-	ns	
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	200	-		

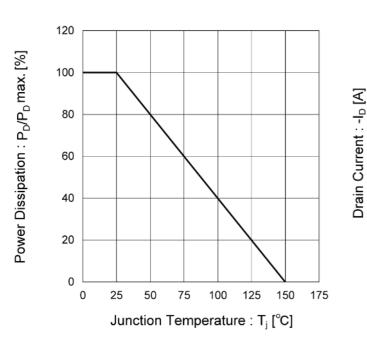
# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Symbol	Conditions		Values			Unit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*4}$	V <sub>DD</sub> ≃ -20V	V <sub>GS</sub> = -10V	-	105.0	-	
				-	52.0	-	nC
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = -35A	V <sub>GS</sub> = -4.5V	-	17.3	-	nc
Gate - Drain charge	Q <sub>gd</sub> *4			-	18.8	-	

# •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Sumbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>S</sub> *1	T <sub>a</sub> = 25℃	-	-	-70	А
Pulse forward current	$I_{SP}^{*2}$	$T_a = 25 C$	-	-	-140	А
Forward voltage	$V_{SD}^{*4}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = -70A	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -50A, V <sub>GS</sub> =0V	-	34	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/µs	-	27	-	nC





# Fig.1 Power Dissipation Derating Curve

1000 ---------Operation in this area is limited by R<sub>DS</sub>(on) ( V<sub>GS</sub> = -10V ) ++++

Fig.2 Maximum Safe Operating Area

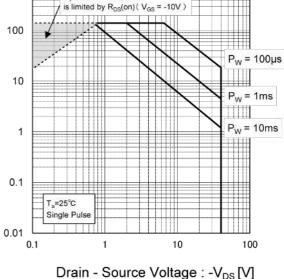
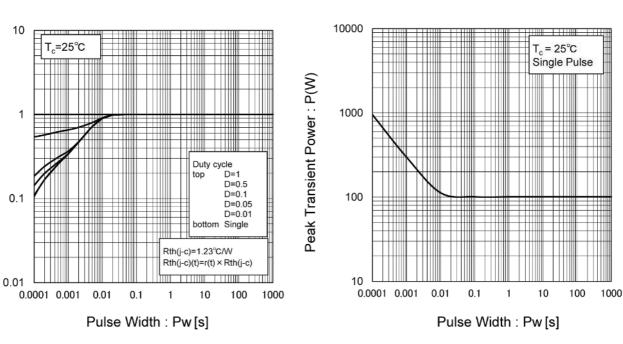


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power Dissipation



Normalized Transient Thermal Resistance :  $r_{\scriptscriptstyle (i)}$ 



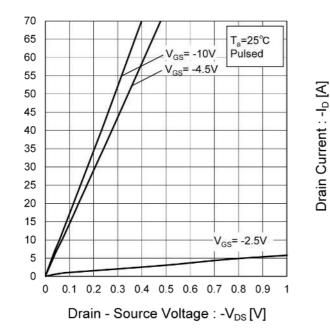


Fig.5 Typical Output Characteristics(I)

# Fig.6 Typical Output Characteristics(II)

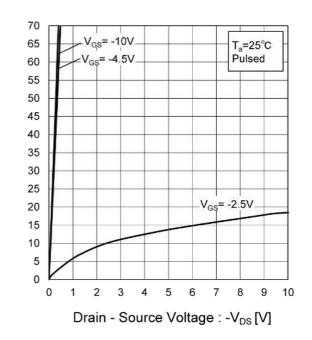
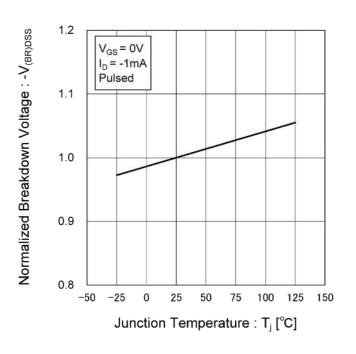
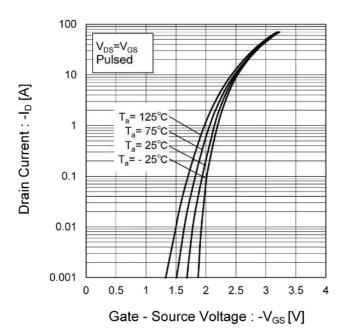


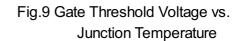
Fig.7 Breakdown Voltage vs. Junction Temperature

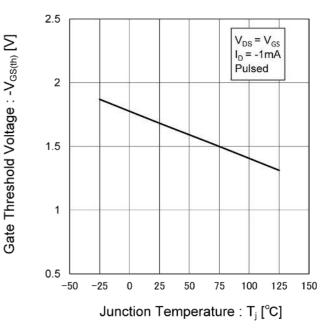




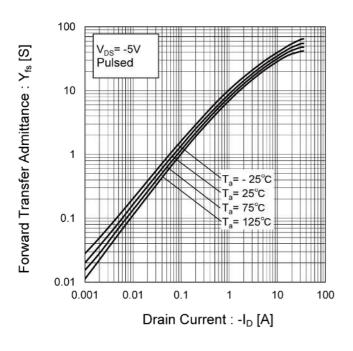


# Fig.8 Typical Transfer Characteristics





# Fig.10 Forward Transfer Admittance vs. Drain Current





# • Electrical characteristic curves

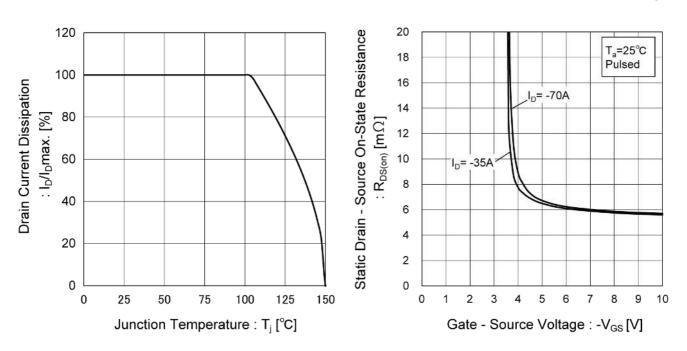
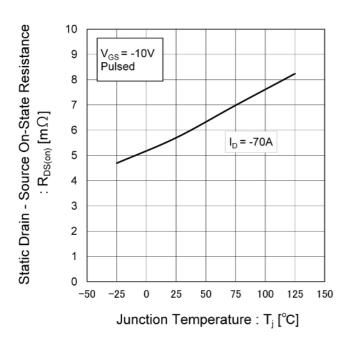


Fig.11 Drain Current Derating Curve

# Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





# • Electrical characteristic curves

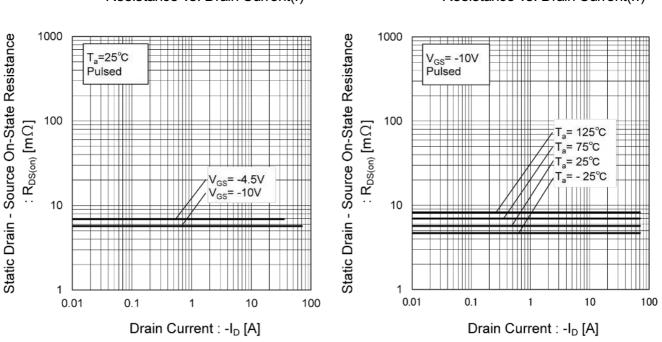
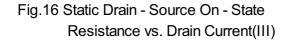
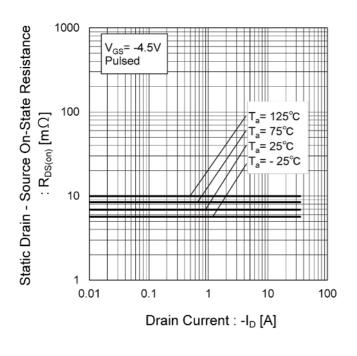


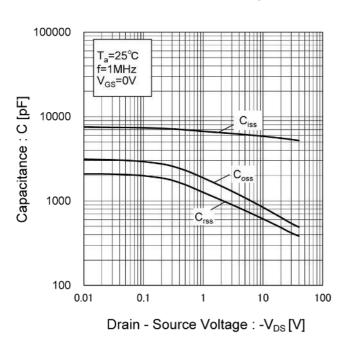
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)







# • Electrical characteristic curves



# Fig.17 Typical Capacitances vs. Drain - Source Voltage

Fig.18 Switching Characteristics

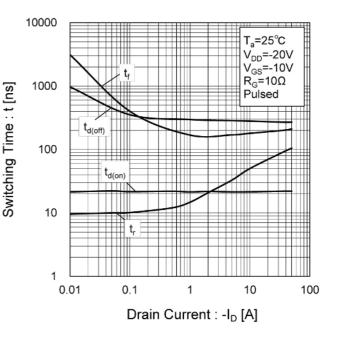


Fig.19 Typical Gate Charge

Gate - Source Voltage : -V<sub>GS</sub> [V]

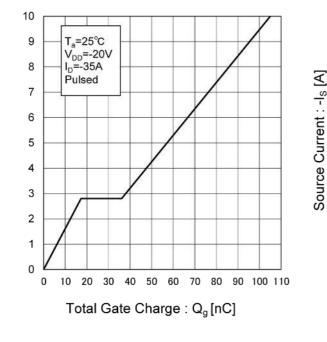
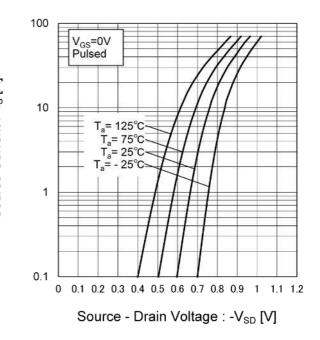


Fig.20 Source Current vs. Source Drain Voltage





### Measurement circuits

#### Fig.1-1 Switching Time Measurement Circuit

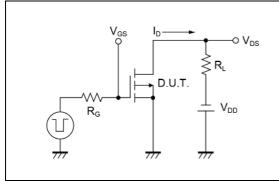
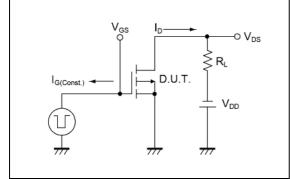
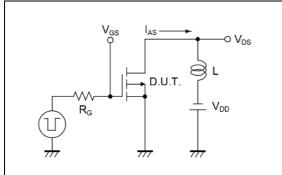


Fig.2-1 Gate Charge Measurement Circuit



#### Fig.3-1 Avalanche Measurement Circuit



#### Fig.1-2 Switching Waveforms

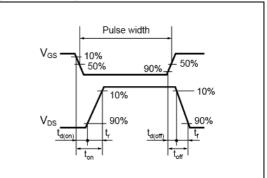
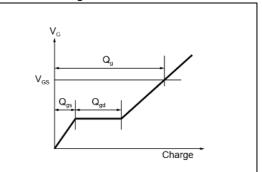
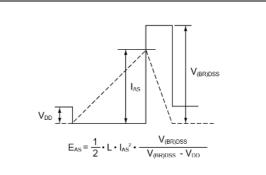


Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform

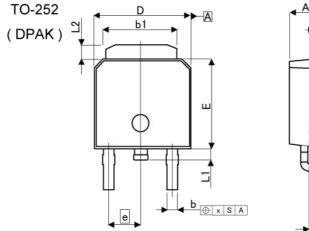


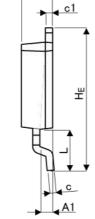
ROHM

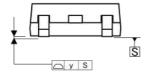


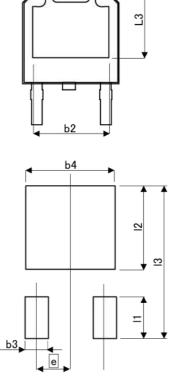
10/11

# Dimensions









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES	
	MIN	MAX	MIN	MAX	
A	2.20	2.40	0.087	0.094	
A1	0.70	1.10	0.028	0.043	
b	0.60	0.90	0.024	0.035	
b1	5.20	5.50	0.205	0.217	
b2	4.	80	0.1	89	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.40	6.80	0.252	0.268	
е	2.	30	0.0	91	
E	6.00	6.40	0.236	0.252	
HE	9.40	10.40	0.370	0.409	
L	2.	90	0.1	114	
L1	0.60	1.00	0.024	0.039	
L2	0.70	1.30	0.028	0.051	
L3	5.	5.30		209	
x	-	0.25	(1)	0.010	
у	73	0.10	15//	0.004	
	MILIME	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b3	+	1.15	2 <del>4</del> 0	0.045	
b4	5	5.55	4.5.3	0.219	
11	÷ (	2.77	( <b>1</b> )	0.109	
12		5.50	3.7.0	0.217	
13	2	10.40	( <b>1</b> )	0.409	

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSI

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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